

AMENDMENTS TO THE SPECIFICATION

Please replace the paragraph beginning on page 3, line 34, with the following amended paragraph:

~~Still~~ A still further object of the present invention is to provide an additive for a CMP abrasive, which CMP abrasive is capable of polishing a surface to be polished at high speed without causing scratches while attaining high level smoothing, and particularly capable of providing the CMP abrasive with an excellent storage stability.